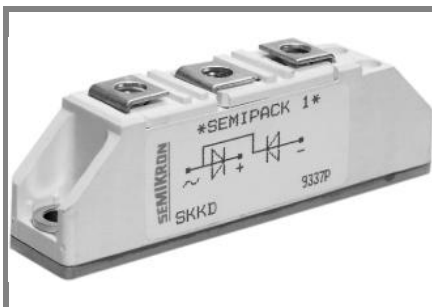


SKKD 105F, SKMD 105F, SKND 105F



SEMIPACK® 1

Fast Diode Modules

SKKD 105F

SKMD 105F

SKND 105F

Features

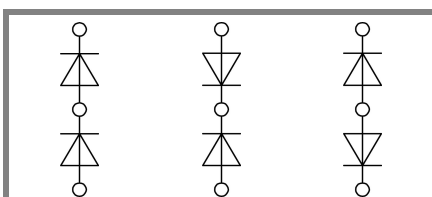
- Heat transfer through ceramic isolated metal baseplate
- Hard soldered joints for high reliability
- SKKD half bridge connection; centre tap connections: SKMD common cathode, SKND common anode
- UL recognized, file no. E 63 532

Typical Applications

- Self-commutated inverters
- DC choppers
- AC motor speed control
- Inductive heating
- Uninterruptible power supplies
- Electronic welders
- General power switching applications

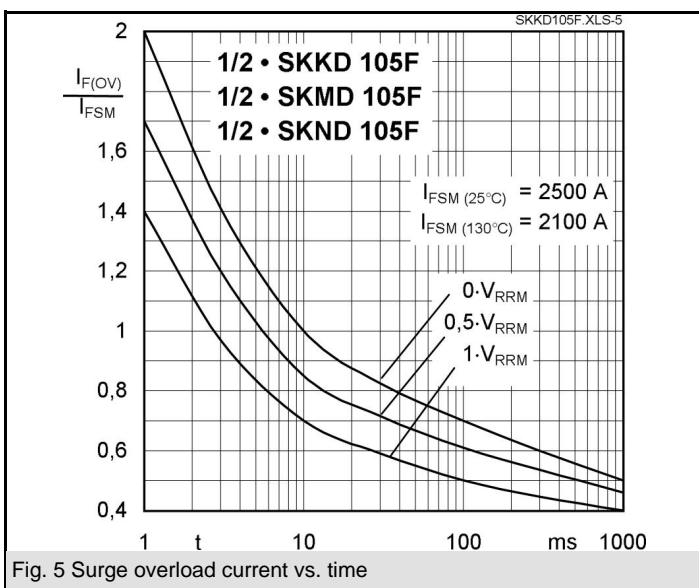
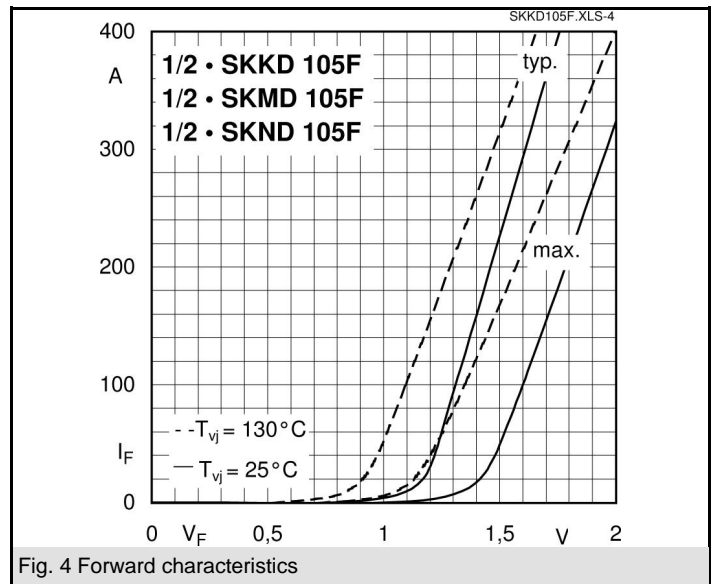
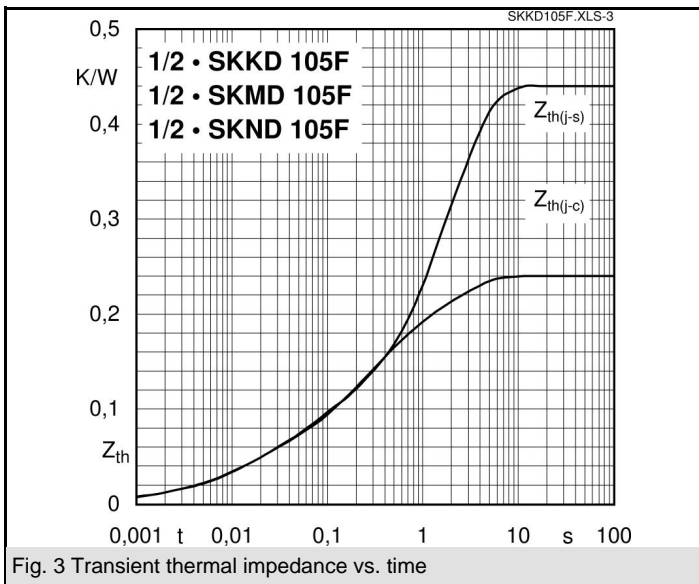
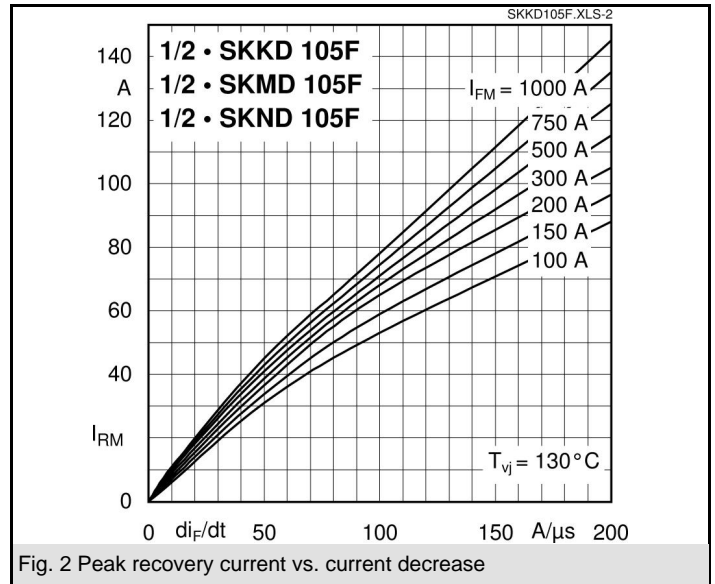
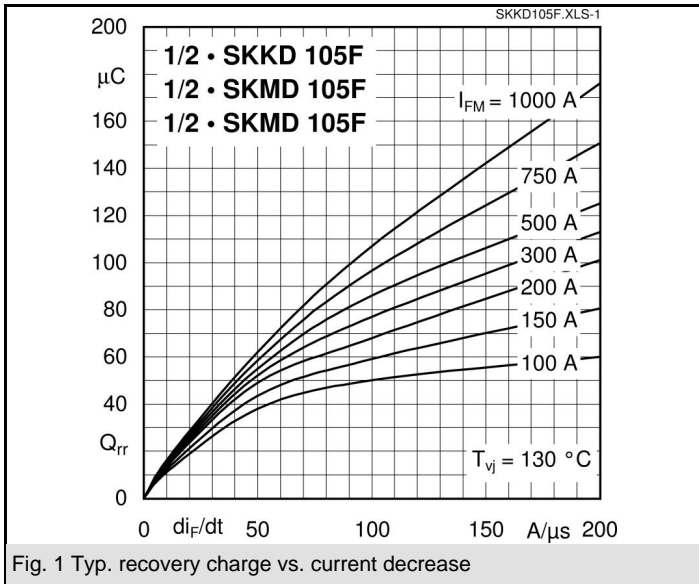
V_{RSM} V	V_{RRM} V	$I_{FRMS} = 200$ A (maximum value for continuous operation)		
		$I_{FAV} = 105$ A (sin. 180; $T_c = 83$ °C)		
800	800	SKKD 105F08	SKMD 105F08	SKND 105F08
1000	1000	SKKD 105F10	SKMD 105F10	SKND 105F10
1200	1200	SKKD 105F12	SKMD 105F12	SKND 105F12

Symbol	Conditions	Values	Units
I_{FAV}	sin. 180; $T_c = 85$ (100) °C	102 (65)	A
I_{FSM}	$T_{vj} = 25$ °C; 10 ms $T_{vj} = 130$ °C; 10 ms	2500 2100	A
i^2t	$T_{vj} = 25$ °C; 8,3 ... 10 ms $T_{vj} = 130$ °C; 8,3 ... 10 ms	31250 22000	A ² s A ² s
V_F	$T_{vj} = 25$ °C; $I_F = 300$ A	max. 2,05	V
$V_{(TO)}$	$T_{vj} = 130$ °C	1,2	V
r_T	$T_{vj} = 130$ °C	2,5	mΩ
I_{RD}	$T_{vj} = 25$ °C; $V_{RD} = V_{RRM}$	max. 1	mA
I_{RD}	$T_{vj} = 130$ °C; $V_{RD} = V_{RRM}$	max. 30	mA
Q_{rr}	under following conditions $T_{vj} = 130$ °C, $I_F = 100$ A,	50	μC
I_{RM}	$-di/dt = 50$ A/μs, $V_R = 30$ V	53	A
t_{rr}		1890	ns
E_{rr}		0,8	mJ
$R_{th(j-c)}$	per diode / per module	0,24 / 0,12	K/W
$R_{th(c-s)}$	per diode / per module	0,2 / 0,1	K/W
T_{vj}		- 40 ... + 130	°C
T_{stg}		- 40 ... + 125	°C
V_{isol}	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3600 / 3000	V~
M_s	to heatsink	5 ± 15 %	Nm
M_t	to terminals	3 ± 15 %	Nm
a		5 * 9,81	m/s ²
m	approx.	120	g
Case	SKKD	A 10	
	SKMD	A 33	
	SKND	A 37	

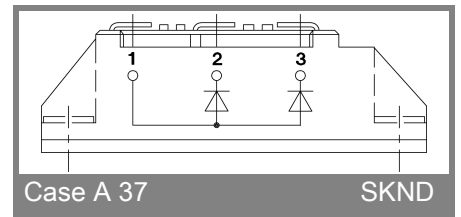
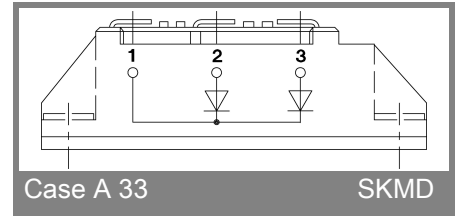
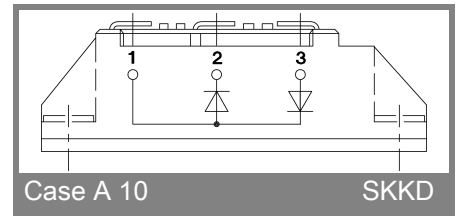
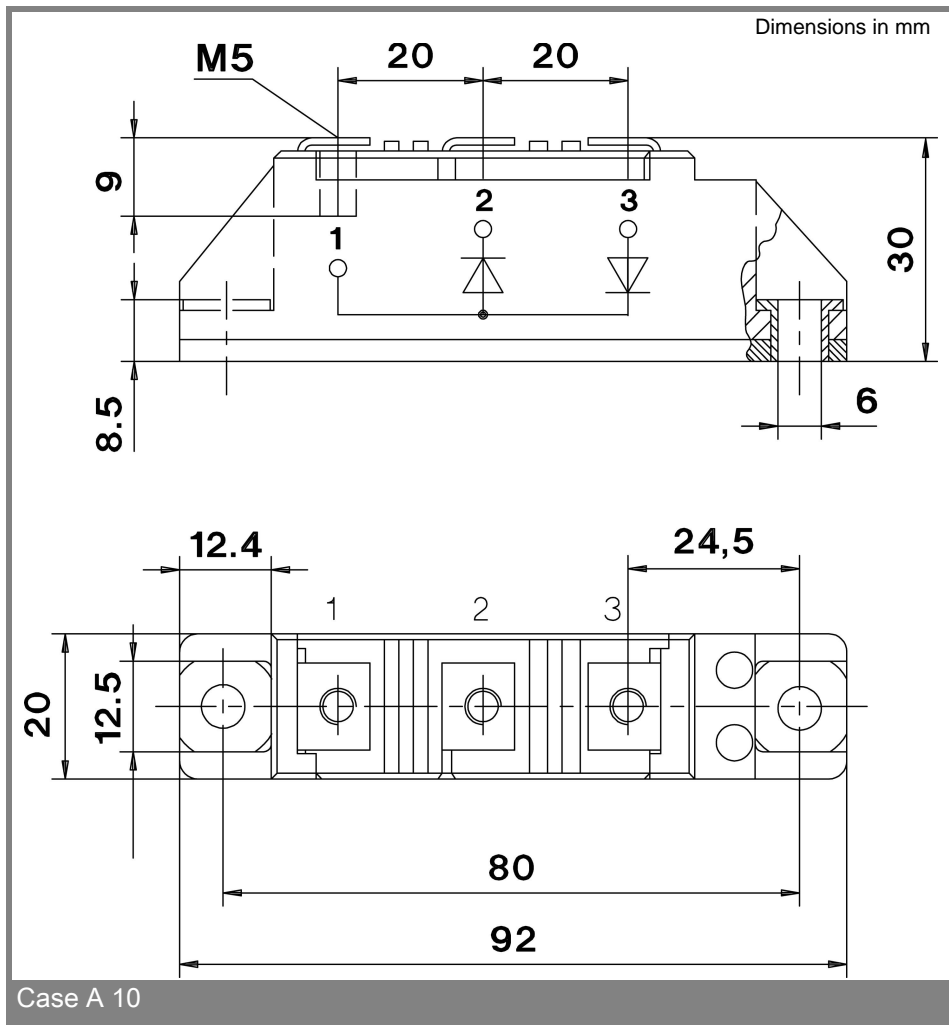


SKKD SKMD SKND

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